

a pump for supplying said liquid in said tank to said pipe at a pressure, or a gas supply unit for supplying a gas into said tank so as to supply said liquid in said tank to said pipe at a pressure;

a control unit for controlling the pressure of said liquid in said pipe at a flow rate;  
and

a spray unit for spraying said liquid supplied from said pipe into said mixing unit.

5. (Twice Amended) The apparatus according to claim 3, wherein said control unit includes a flow meter for measuring the flow rate of liquids in said pipe, said control unit controlling a rotating speed of said pump or controlling the pressure of said gas supplied from said gas supply unit on the basis of the results of measurements by said flow meter.

10. (Twice Amended) A method of supplying a polishing solution in an apparatus including a polishing solution supply system, the polishing solution supply system comprising:

a polishing table for placing a semiconductor substrate on a major surface thereof;  
a first supply unit for spraying and supplying a mist comprising [additive] abrasive slurry; a second supply unit for spraying and supplying a mist comprising additive; a third supply unit for spraying and supplying a mist comprising pure water; and a mixing unit for mixing the mist of abrasive slurry unit and the mist of pure water supplied from said third supply unit to form a polishing mixture, said mixing unit supplying the polishing mixture onto said major surface of said polishing table;